



SOT973-2

plastic, thermal enhanced extremely thin small outline package; no leads; 12 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2514-12
Package type industry code	DFN2514-12
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	25-3-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	



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2. Package outline

HXSON12: plastic, thermal enhanced extremely thin small outline package; no leads; 12 terminals; body 1.35 x 2.5 x 0.5 mm

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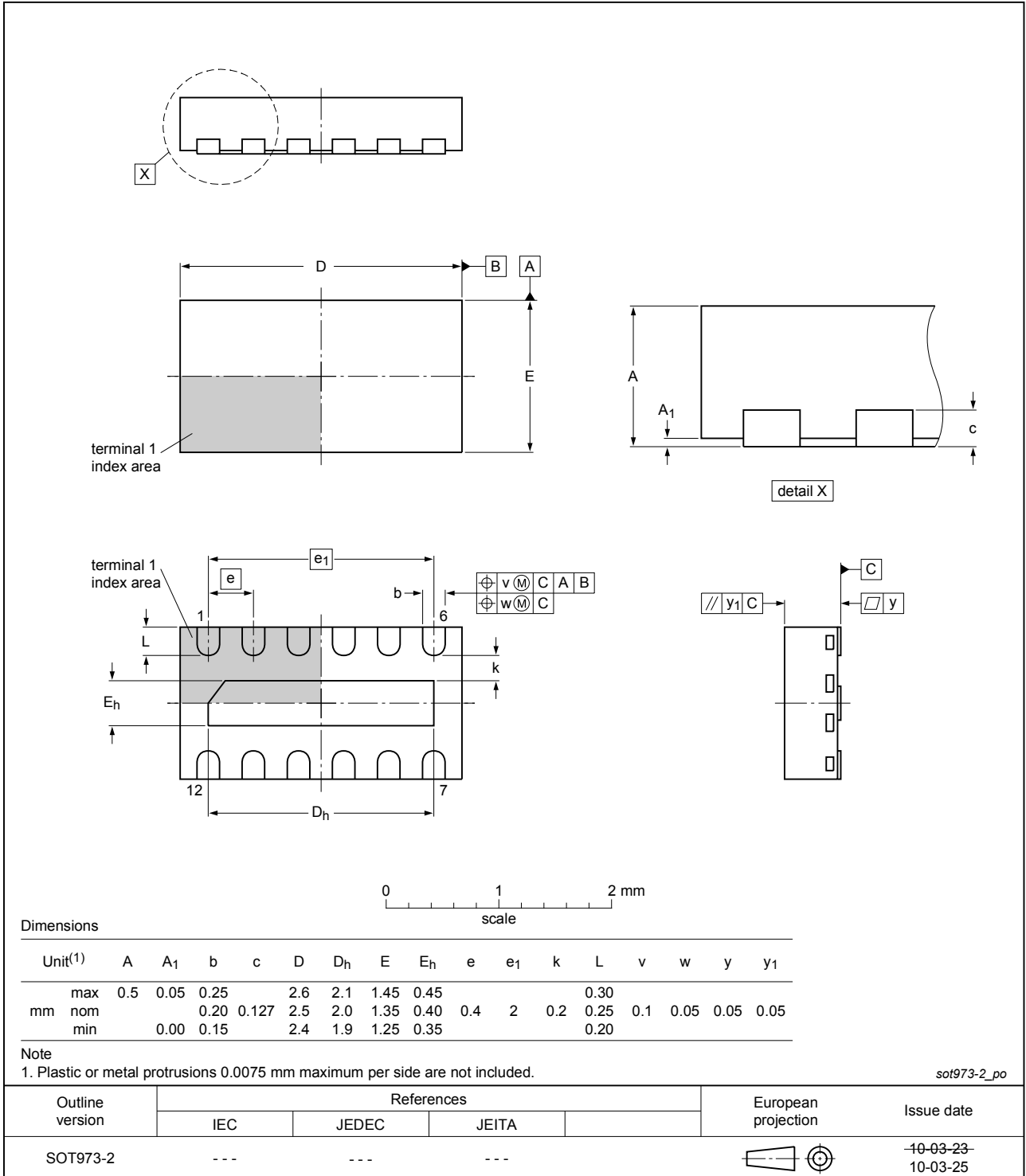


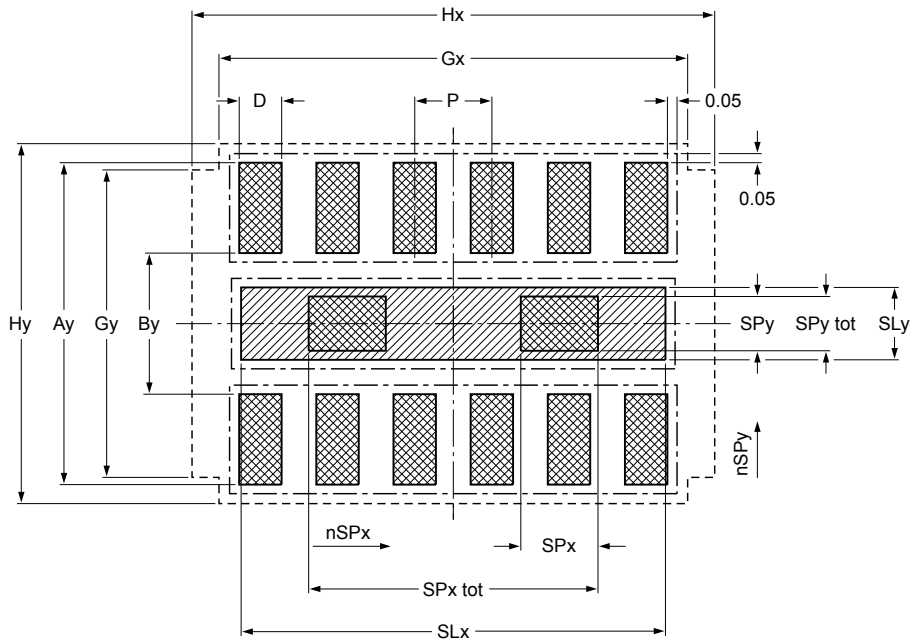
Fig. 1. Package outline DFN2514-12 (SOT973-2)

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3. Soldering

Footprint information for reflow soldering of HXSON12 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist

DIMENSIONS in mm

P	Ay	By	D	Slx	Sly	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy	nSPx	nSPy
0.400	1.780	0.780	0.220	2.200	0.400	1.500	0.300	0.400	0.300	2.430	1.700	2.710	1.990	2	1

Issue date 12-08-15
12-08-28

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Fig. 2. Reflow soldering footprint for DFN2514-12 (SOT973-2)

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4. Legal information

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